SDLS004 D2633, JANUARY 1981—REVISED MARCH 1988

- **Parallel Register Inputs ('LS592)**
- **Parallel 3-State I/O: Register Inputs/ Counter Outputs ('LS593)**
- **Counter has Direct Overriding Load and Clear**
- **Accurate Counter Frequency: DC to 20 MHz**

description

The 'LS592 comes in a 16-pin package and consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive-edge-triggered clocks. In addition, the counter has direct load and clear functions. A low-going $\overline{RCO}$ pulse will be obtained when the counter reaches the hex word FF. Expansion is easily accomplished for two stages by connecting $\overline{RCO}$ of the first stage to $\overline{CCKEN}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{RCO}$ of each stage to CCK of the following stage.

The 'LS593 comes in a 20-pin package and has all the features of the 'LS592 plus 3-state I/O, which provides parallel counter outputs. The tables below show the operation of the enable (CCKEN, $\overline{CCKEN}$) inputs. A register clock enable ($\overline{RCKEN}$) is also provided.

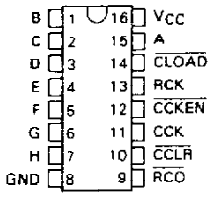
OUTPUT ENABLE CONTROL ('593 ONLY)

G	$\overline{G}$	A/Q_A thru H/Q_H
L	L	input mode
L	H	input mode
H	L	output mode
H	H	input mode

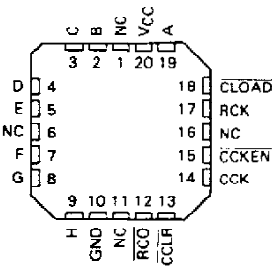
COUNTER CLOCK ENABLE CONTROL

CCKEN	$\overline{CCKEN}$	EFFECT ON CCK
L	L	Enable
L	H	Disable
H	L	Enable
H	H	Enable

SN54LS592 . . . J OR W PACKAGE
SN74LS592 . . . N PACKAGE
(TOP VIEW)

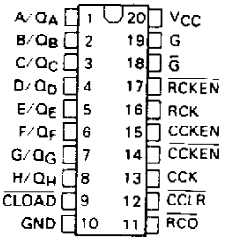


SN54LS592 . . . FK PACKAGE
(TOP VIEW)

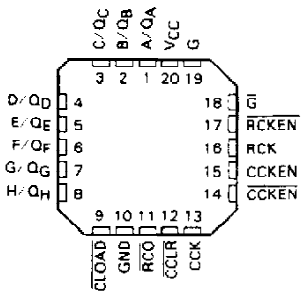


NC — No internal connection

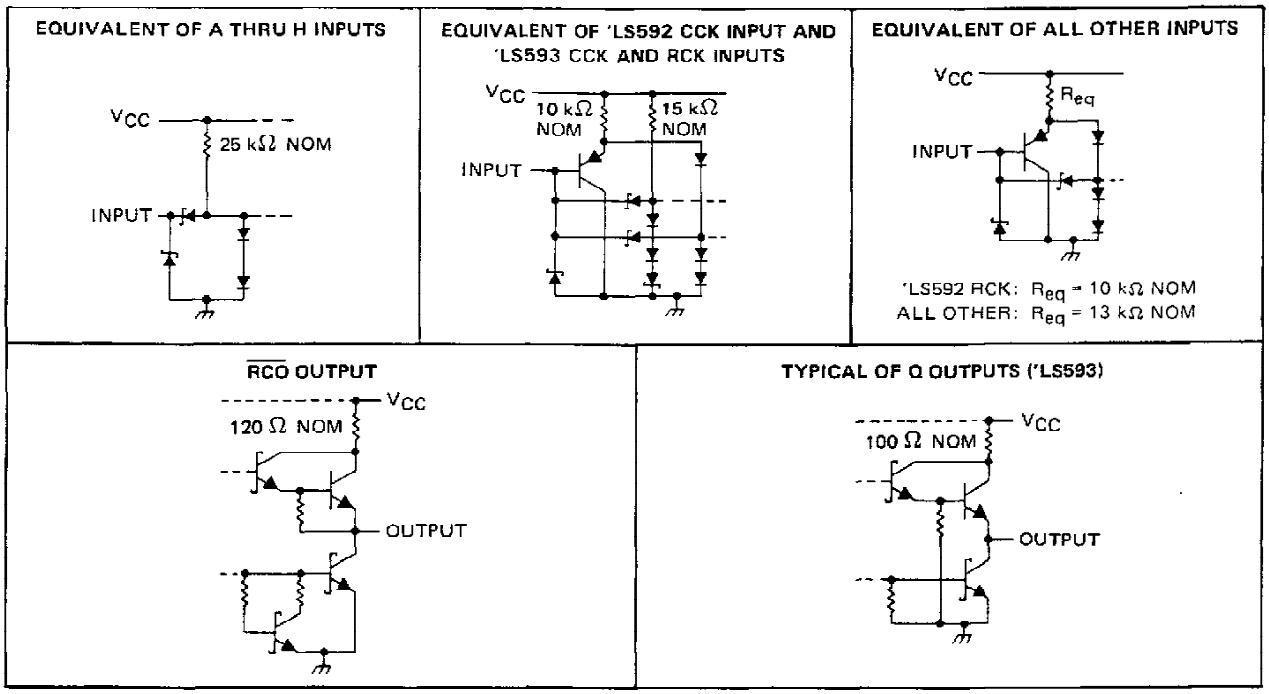
SN54LS593 . . . J OR W PACKAGE
SN74LS593 . . . DW OR N PACKAGE
(TOP VIEW)



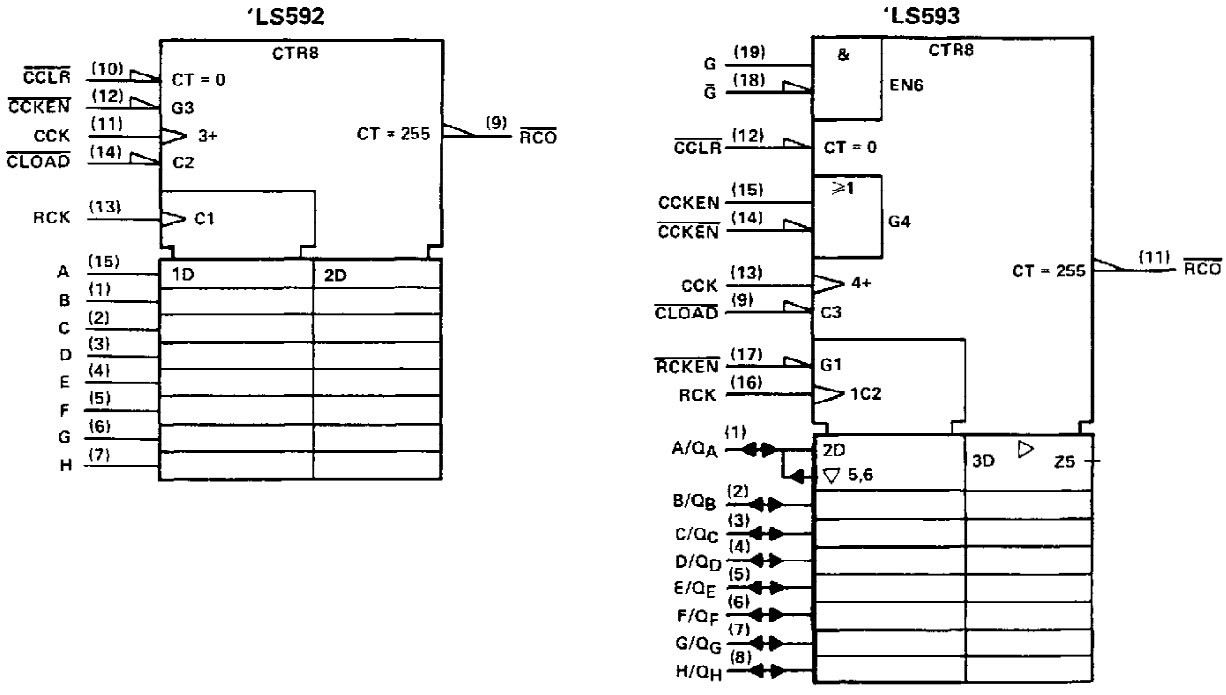
SN54LS593 . . . FK PACKAGE
(TOP VIEW)



schematics of inputs and outputs

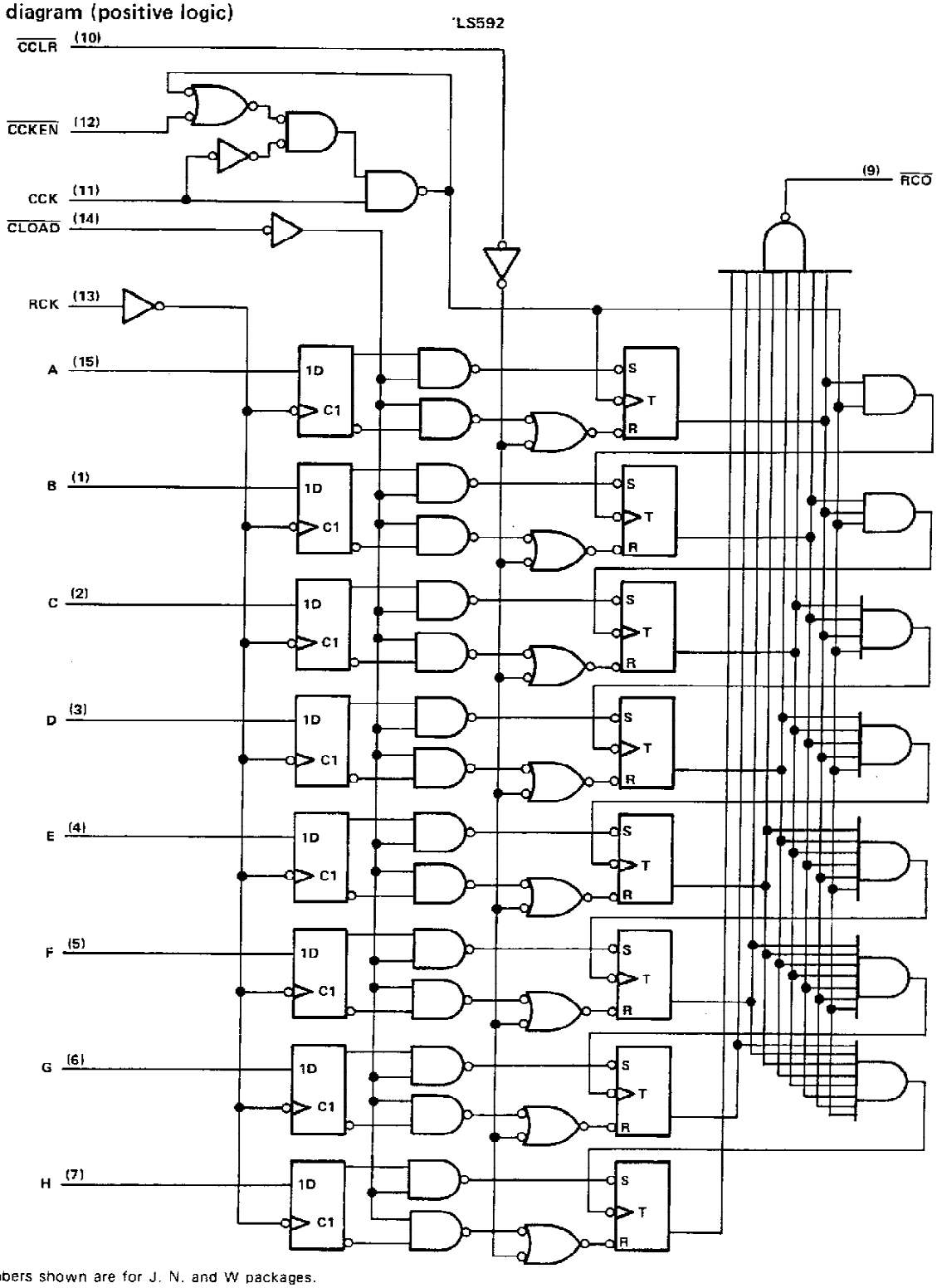


logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, N, and W packages.

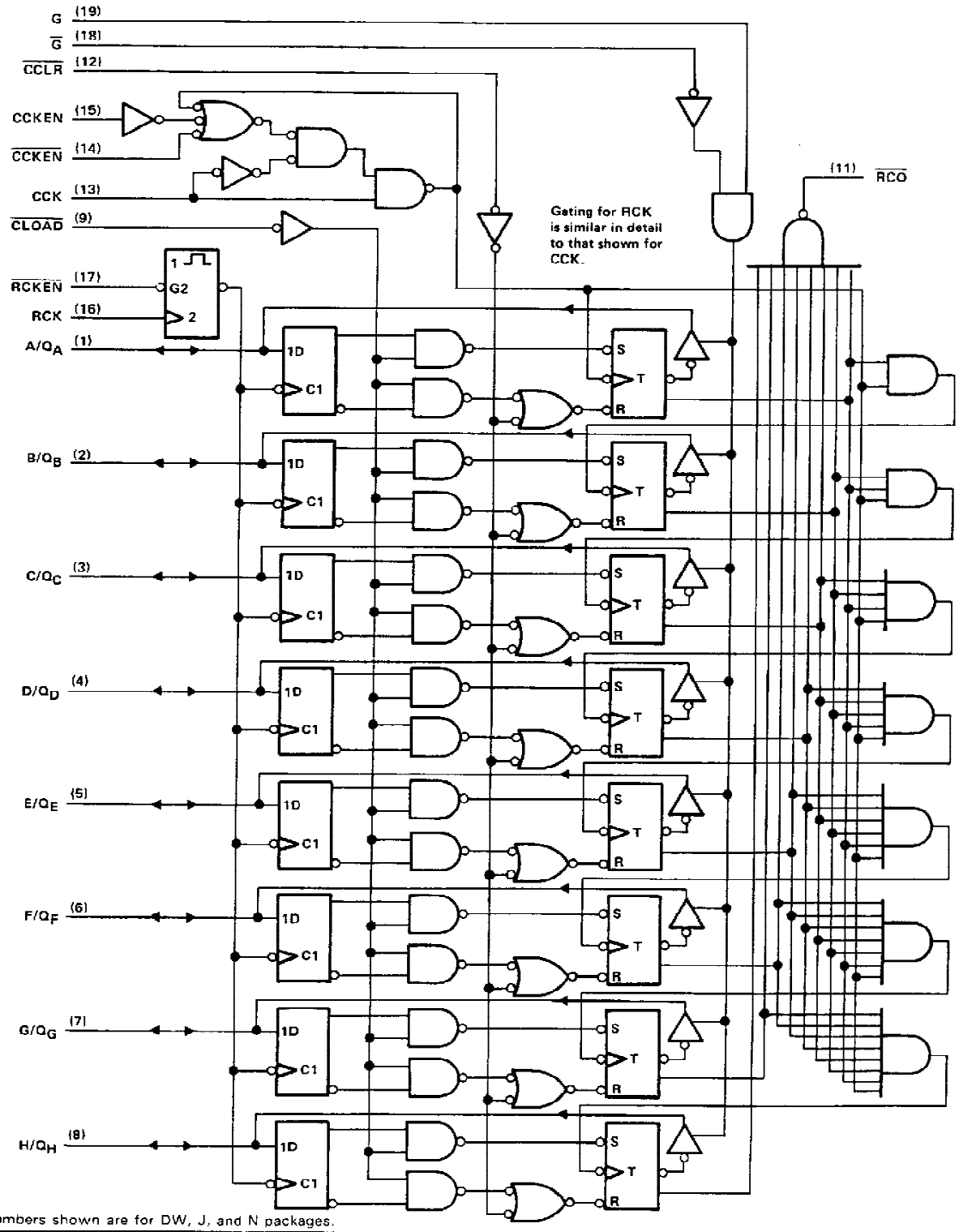
logic diagram (positive logic)



Pin numbers shown are for J, N, and W packages.

logic diagram (positive logic)

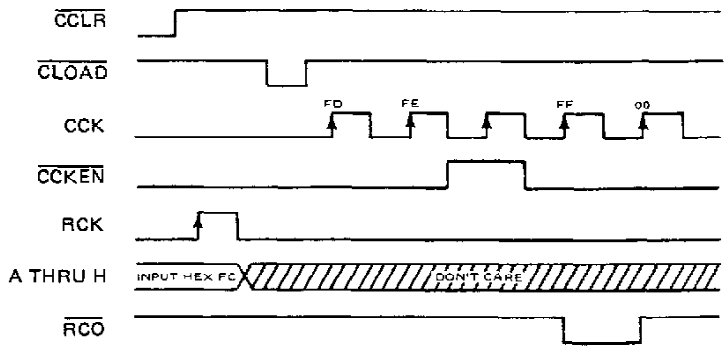
'LS593



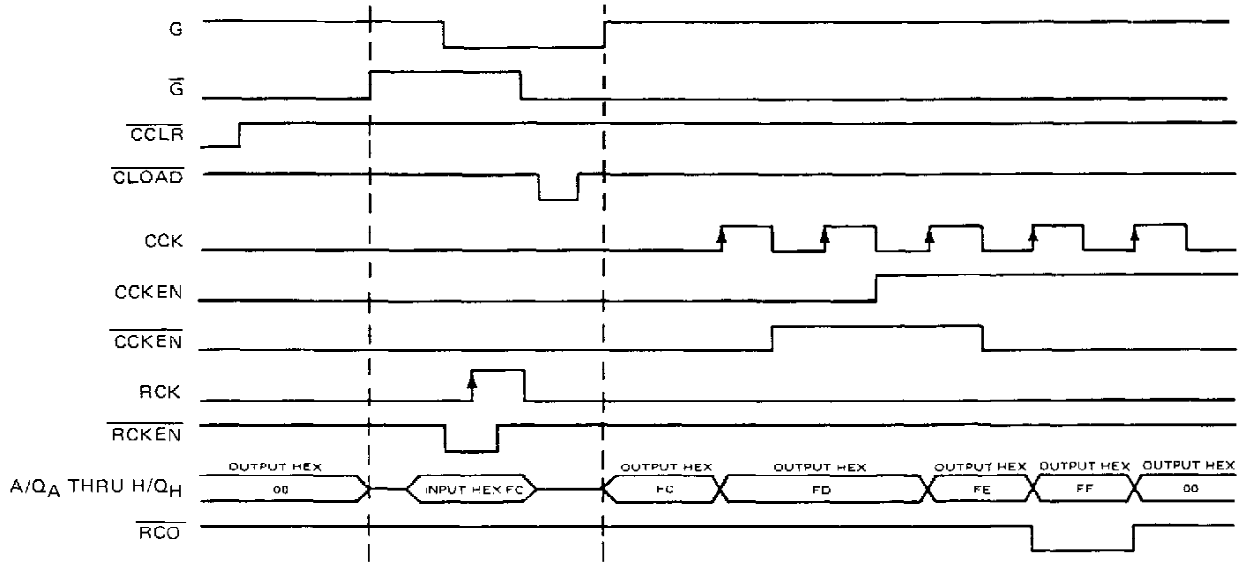
Pin numbers shown are for DW, J, and N packages.

typical operating sequences

'LS592



'LS593



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage (excluding I/O ports) . . . . . 7 V
Off-state output voltage (including I/O ports) . . . . . 5.5 V
Operating free-air temperature range: SN54LS592, SN54LS593 . . . . . −55°C to 125°C
SN74LS592, SN74LS593 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

			SN54LS'			SN74LS'			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current	$\overline{RCO}$			−1			−1	mA
		Q 'LS593 only			−1			−2.6	
I_{OL}	Low-level output current	$\overline{RCO}$			8			16	mA
		Q 'LS593 only			12			24	
f_{CCK}	Counter clock frequency		0		20	0		20	MHz
t_{w} (CCK)	Duration of counter clock pulse		25			25			ns
t_{w} ($\overline{CCLR}$)	Duration of counter clear pulse		20			20			ns
t_{w} (RCK)	Duration of register clock pulse		20			20			ns
t_{w} ($\overline{CLOAD}$)	Duration of counter load pulse		40			40			ns
t_{su}	Register enable setup time	$\overline{RCKEN}$ low to RCK ↑, 'LS593	20			20			ns
t_{su}	Counter enable setup time before CCK ↑	$\overline{CCKEN}$ low, 'LS592	30			30			ns
		$\overline{CCKEN}$ low or CCKEN high, 'LS593	30			30			
t_{su}	Setup time	$\overline{CCLR}$ inactive before CCK ↑	20			20			ns
		$\overline{CLOAD}$ inactive before CCK ↑	20			20			
		RCK ↑ before $\overline{CLOAD}$ ↑ (see Note 2)	30			30			
		Data A thru H before RCK ↑	20			20			
t_{h}	Hold time	Data A thru H after RCK ↑	0			0			ns
		All others	0			0			
T_{A}	Operating free-air temperature		−55		125	0		70	°C

NOTE 2: This time insures the data saved by RCK ↑ will also be loaded into the counter.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS' MIN	SN54LS' TYP‡	SN54LS' MAX	SN74LS' MIN	SN74LS' TYP‡	SN74LS' MAX	UNIT
V_{IK}			V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	'LS593 Q		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OH} = −1 mA	2.4	3.2					V
				I_{OH} = −2.6 mA				2.4	3.1		
	$\overline{RCO}$			I_{OH} = −1 mA	2.4	3.2		2.4	3.2		
V_{OL}	'LS593 Q		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 24 mA					0.35	0.5	
	$\overline{RCO}$			I_{OL} = 8 mA		0.25	0.4		0.25	0.4	
				I_{OL} = 16 mA					0.35	0.5	
I_{OZH}	'LS593 Q		V_{CC} = MAX, V_{IH} = 2 V, V_{IL} = MAX, V_O = 2.7 V				20			20	μA
I_{OZL}	'LS593 Q		V_{CC} = MAX, V_{IH} = 2 V, V_{IL} = MAX, V_O = 0.4 V				−0.4			−0.4	mA
I_I	'LS593 Q		V_{CC} = MAX	V_I = 5.5 V			0.1			0.1	mA
	Others			V_I = 7 V			0.1			0.1	
I_{IH}			V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	CCK		V_{CC} = MAX, V_I = 0.4 V				−0.8			−0.8	mA
	RCK	'LS592					−0.2			−0.2	
		'LS593					−0.8			−0.8	
	A thru H						−0.4			−0.4	
	Others						−0.2			−0.2	
I_{OS}§	'LS593 Q		V_{CC} = MAX, V_O = 0 V		−30		−130	−30		−130	mA
	$\overline{RCO}$				−20		−100	−20		−100	
I_{CC}	'LS592	I_{CCH}	V_{CC} = MAX, All possible inputs grounded, All outputs open			40	60		40	60	mA
		I_{CCL}				40	60		40	60	
	'LS593	I_{CCH}				47	70		47	70	
		I_{CCL}				53	80		53	80	
		I_{CCZ}				57	85		57	85	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS592			'LS593			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	CCK	$\overline{RCO}$	R_L = 1 kΩ, C_L = 30 pF	20	35		20	35		MHz
t_{PLH}	CCK ↑	Q	R_L = 667 Ω, C_L = 45 pF					14	21	ns
t_{PHL}	CCK ↑	Q						26	39	ns
t_{PLH}	$\overline{CLOAD}$ ↓	Q						34	51	ns
t_{PHL}	$\overline{CLOAD}$ ↓	Q						28	42	ns
t_{PHL}	$\overline{CCLR}$ ↓	Q						25	38	ns
t_{PZH}	G ↑	Q						31	47	ns
t_{PZL}	G ↑	Q						27	40	ns
t_{PZH}	$\overline{G}$ ↓	Q						29	45	ns
t_{PZL}	$\overline{G}$ ↓	Q						31	47	ns
t_{PHZ}	G ↓	Q	R_L = 667 Ω, C_L = 5 pF					33	50	ns
t_{PLZ}	G ↓	Q						35	52	ns
t_{PHZ}	$\overline{G}$ ↑	Q						26	39	ns
t_{PLZ}	$\overline{G}$ ↑	Q						28	42	ns
t_{PLH}	CCK ↑	$\overline{RCO}$	R_L = 1 kΩ, C_L = 30 pF		15	23		14	21	ns
t_{PHL}	CCK ↑	$\overline{RCO}$			20	30		20	30	ns
t_{PLH}	$\overline{CLOAD}$ ↓	$\overline{RCO}$			31	47		31	47	ns
t_{PHL}	$\overline{CLOAD}$ ↓	$\overline{RCO}$			27	41		27	41	ns
t_{PLH}	$\overline{CCLR}$ ↓	$\overline{RCO}$			30	45		30	45	ns
t_{PLH}	RCK ↑	$\overline{RCO}$	R_L = 1 kΩ; C_L = 30 pF $\overline{CLOAD}$ = L		35	53		42	63	ns
t_{PHL}	RCK ↑	$\overline{RCO}$			30	45		33	50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8762101EA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
5962-8762101FA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
5962-8762101FA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SN54LS592J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS592J	Samples
SN54LS592J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS592J	Samples
SN54LS593J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS593J	Samples
SN54LS593J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS593J	Samples
SN74LS592D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS592	Samples
SN74LS592D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS592	Samples
SN74LS592N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS592N	Samples
SN74LS592N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS592N	Samples
SN74LS592NSR	ACTIVE	SOP	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS592	Samples
SN74LS592NSR	ACTIVE	SOP	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS592	Samples
SN74LS593DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	LS593	
SN74LS593DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	LS593	
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS593	Samples
SN74LS593N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS593N	Samples
SN74LS593N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS593N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS592J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
SNJ54LS592J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101EA SNJ54LS592J	Samples
SNJ54LS592W	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SNJ54LS592W	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762101FA SNJ54LS592W	Samples
SNJ54LS593J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS593J	Samples
SNJ54LS593J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS593J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54LS592, SN54LS593, SN74LS592, SN74LS593 :

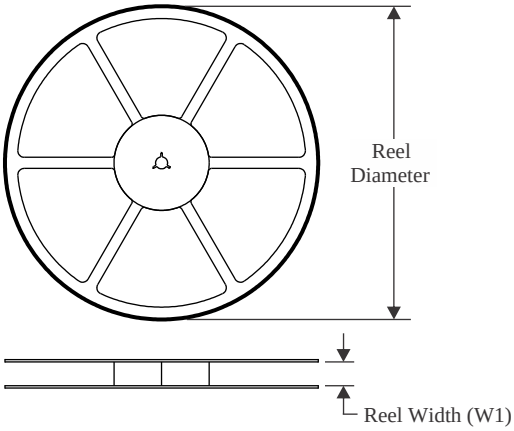
- Catalog : SN74LS592, SN74LS593
- Military : SN54LS592, SN54LS593

NOTE: Qualified Version Definitions:

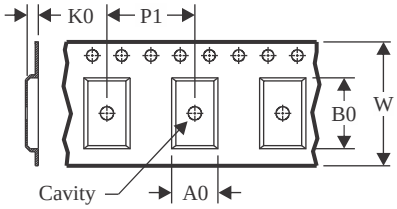
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

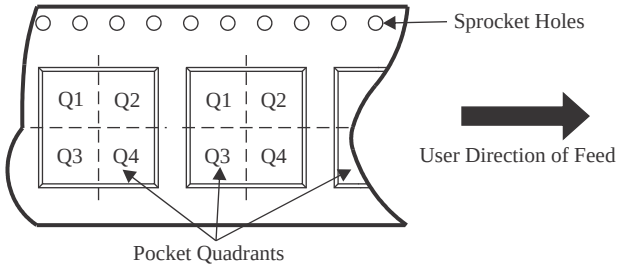


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

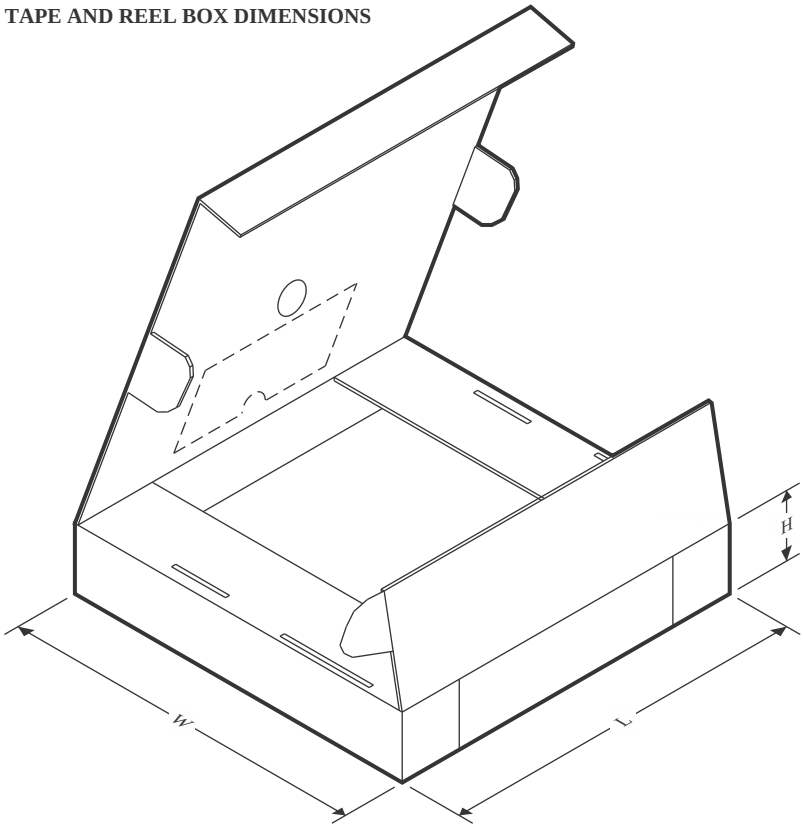
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS592NSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS593DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

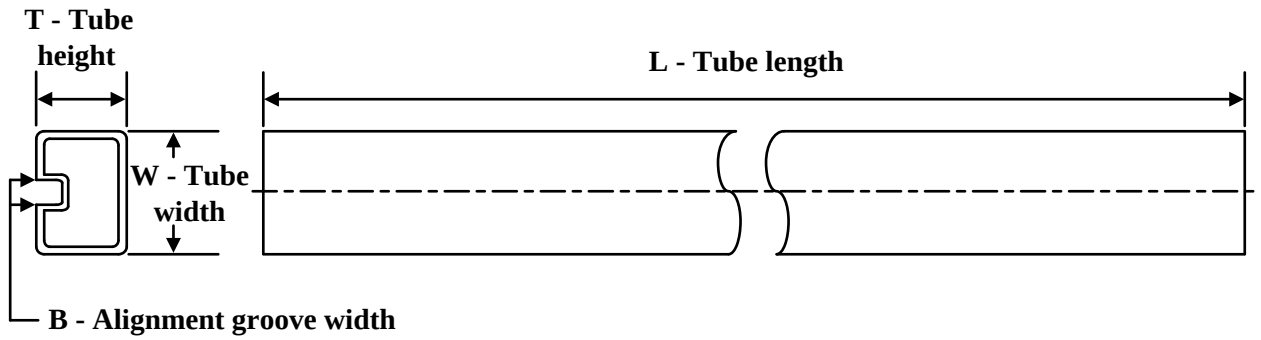
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS592NSR	SOP	NS	16	2000	356.0	356.0	35.0
SN74LS593DWR	SOIC	DW	20	2000	367.0	367.0	45.0

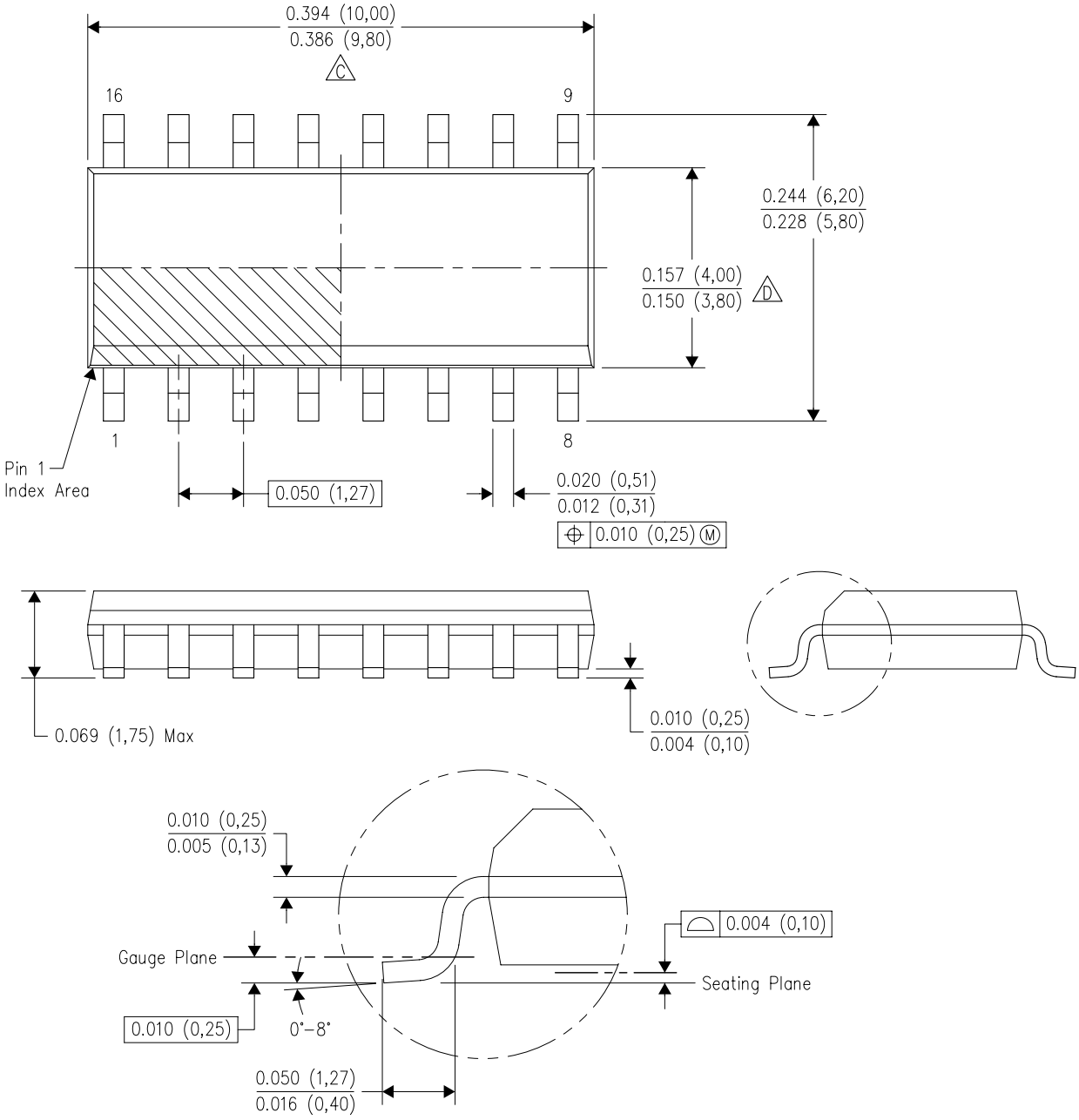
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-8762101FA	W	CFP	16	25	506.98	26.16	6220	NA
SN74LS592D	D	SOIC	16	40	507	8	3940	4.32
SN74LS592N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS592N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS593N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54LS592W	W	CFP	16	25	506.98	26.16	6220	NA

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

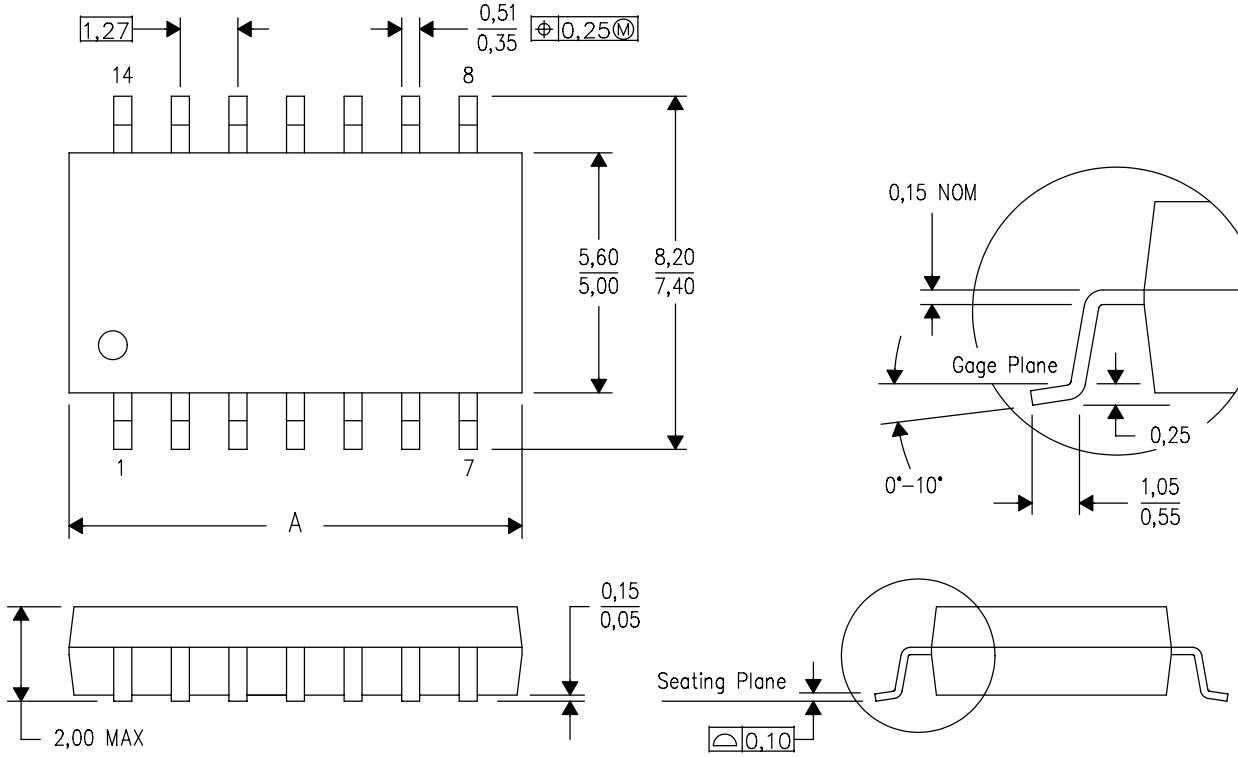


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

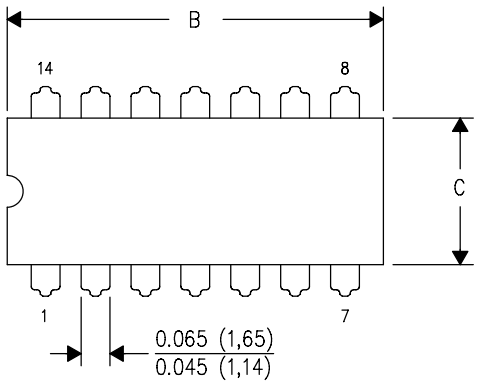
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

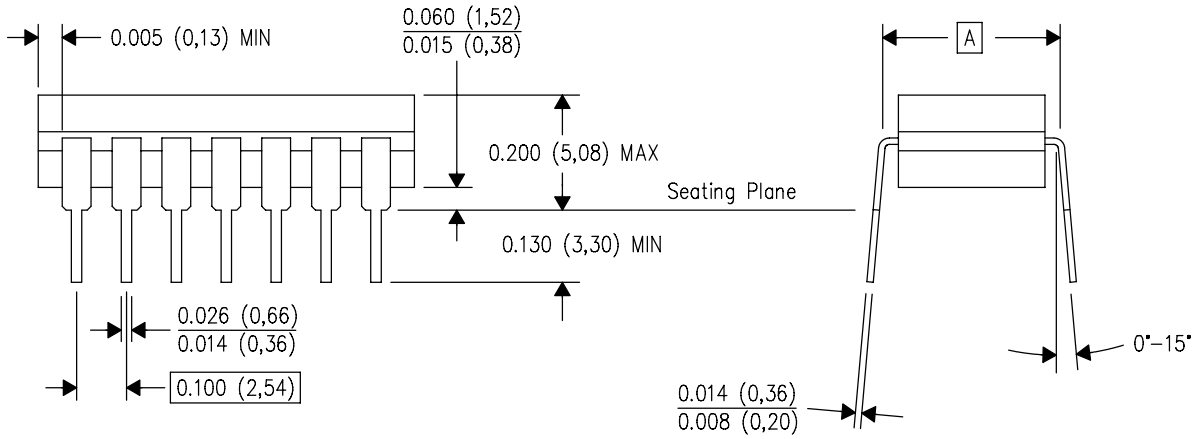
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



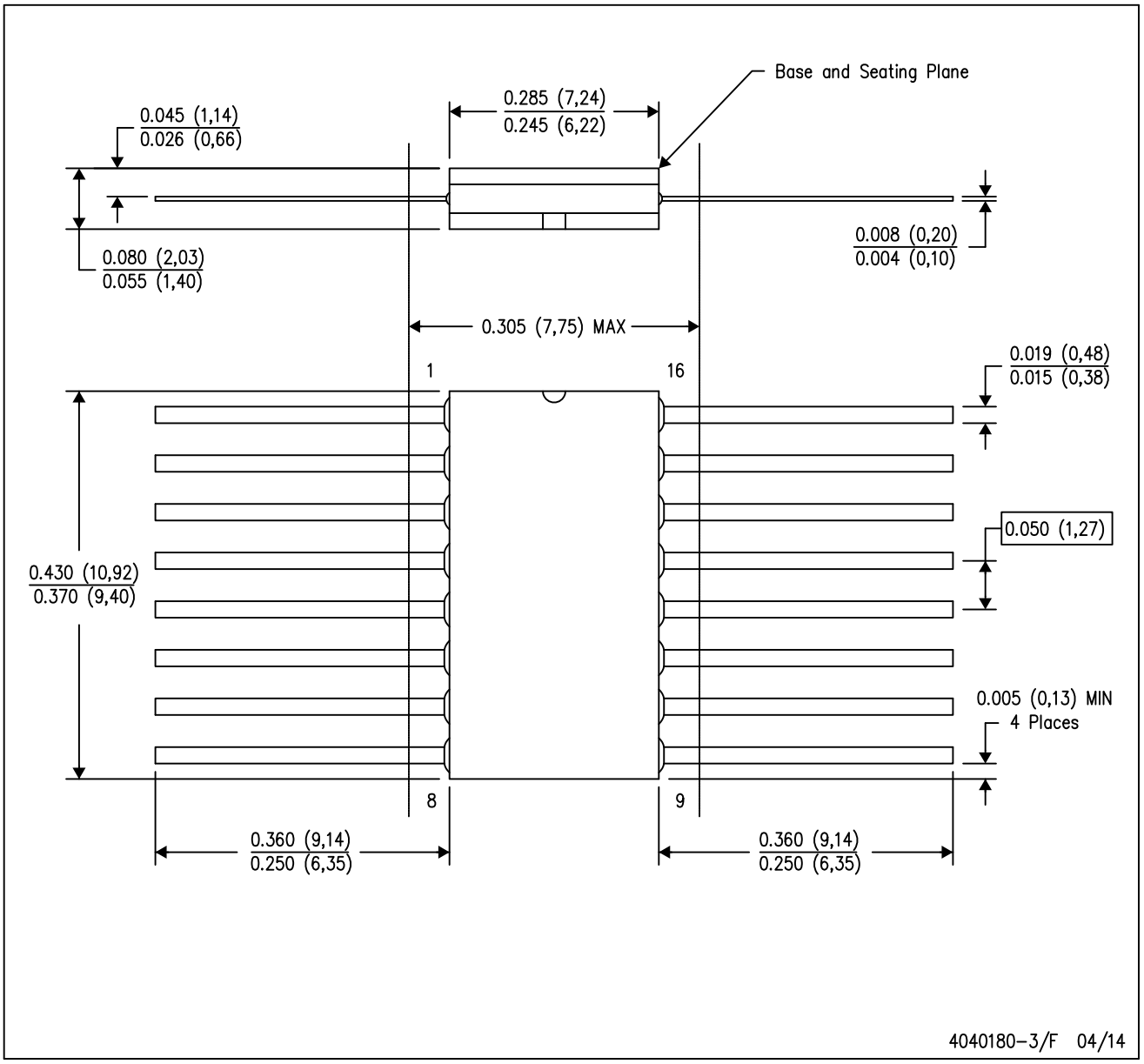
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

W (R–GDFP–F16) CERAMIC DUAL FLATPACK

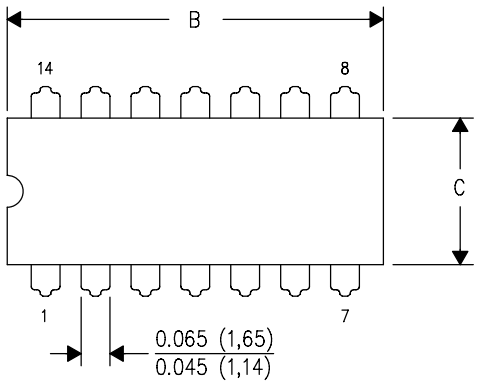


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

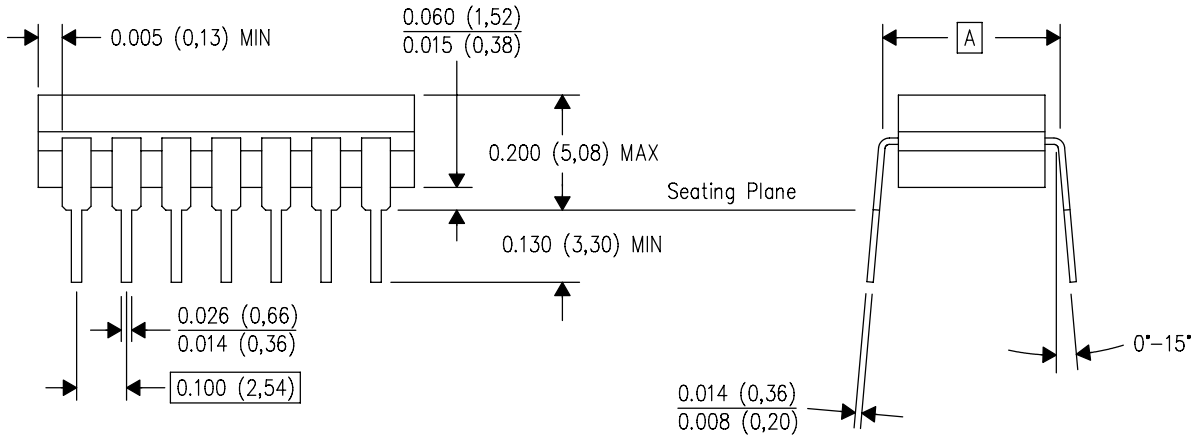
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



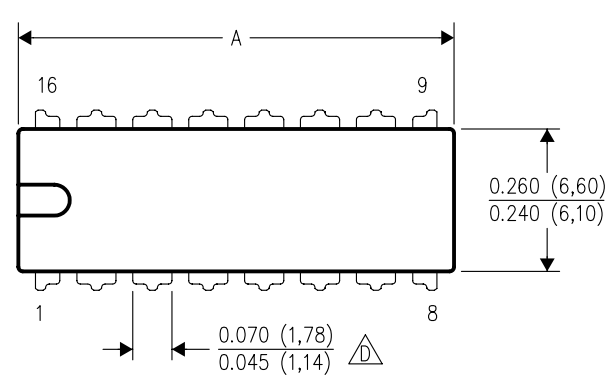
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

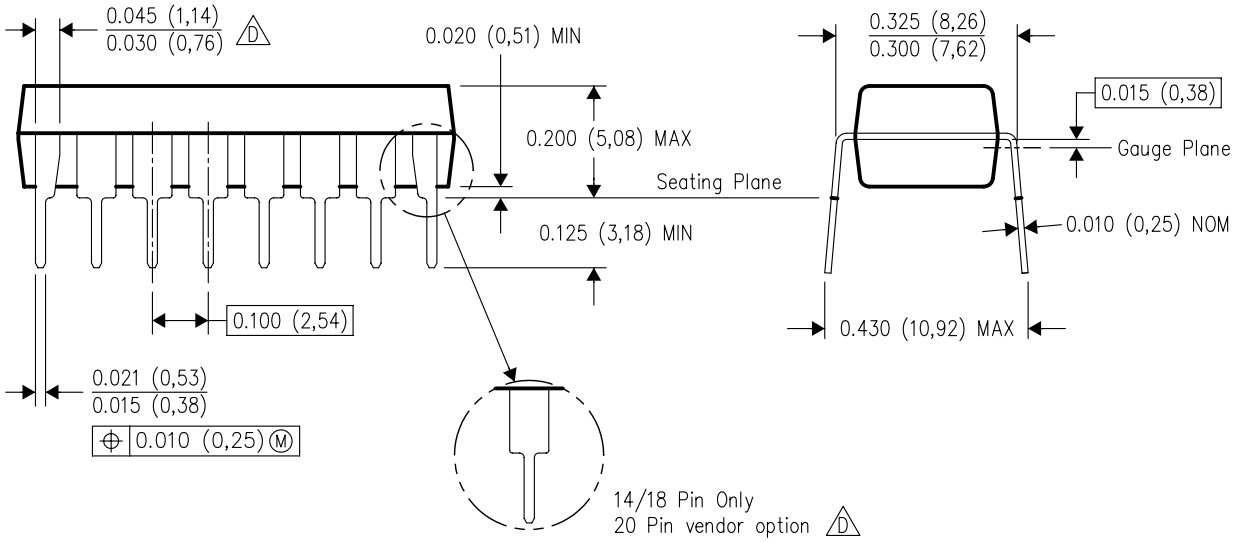
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

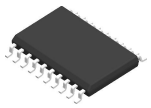


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

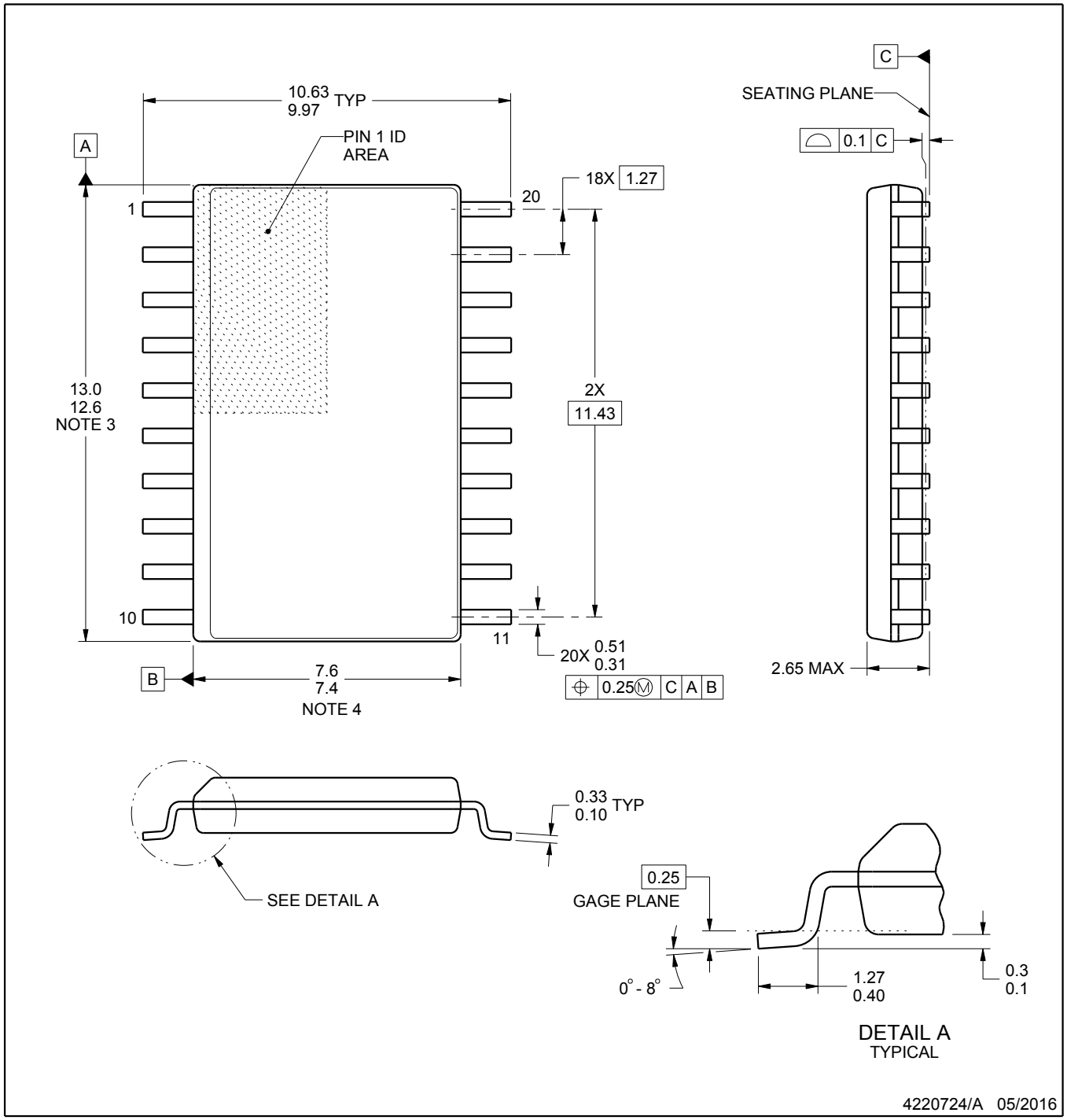


PACKAGE OUTLINE

DW0020A

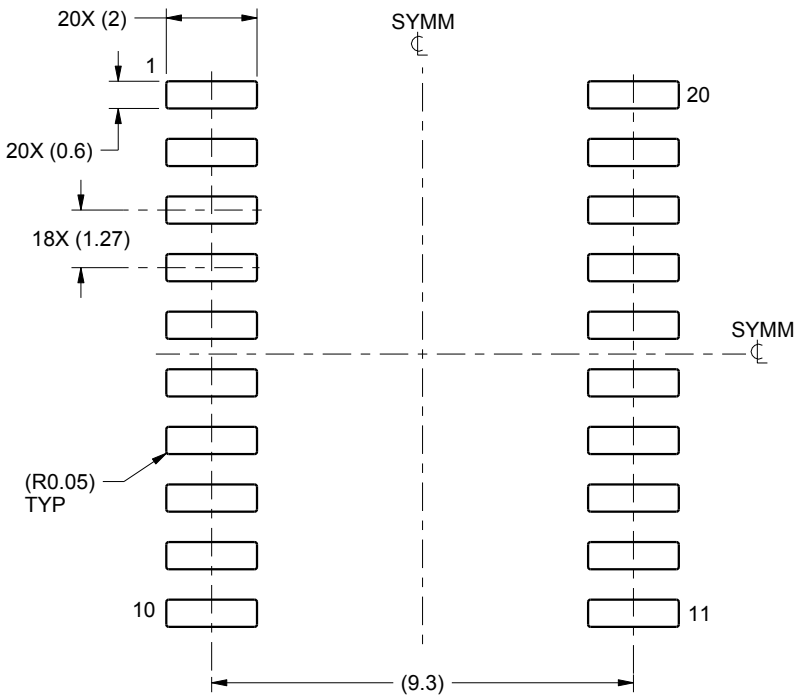
SOIC - 2.65 mm max height

SOIC

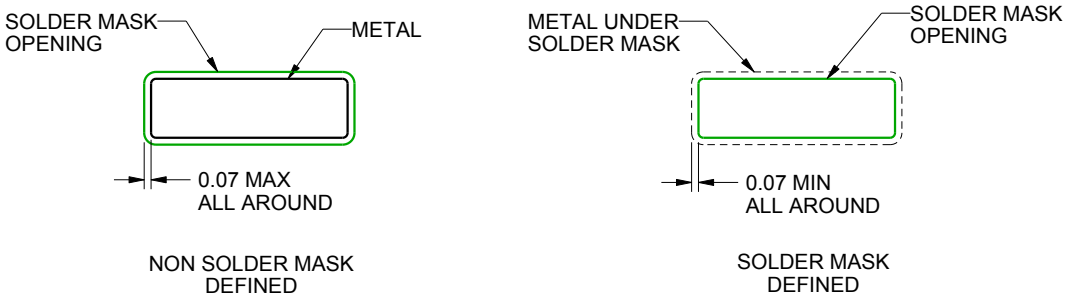


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

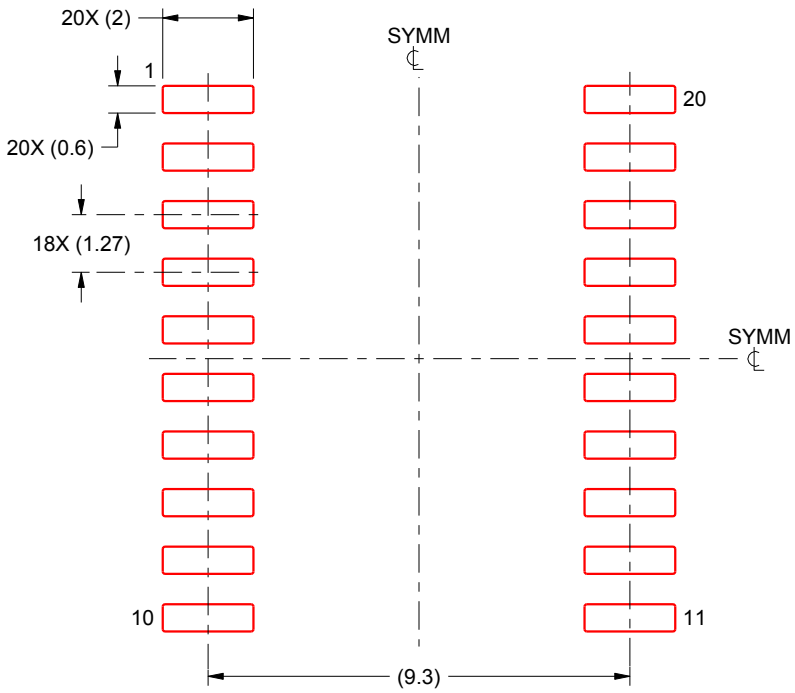


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

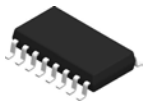


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

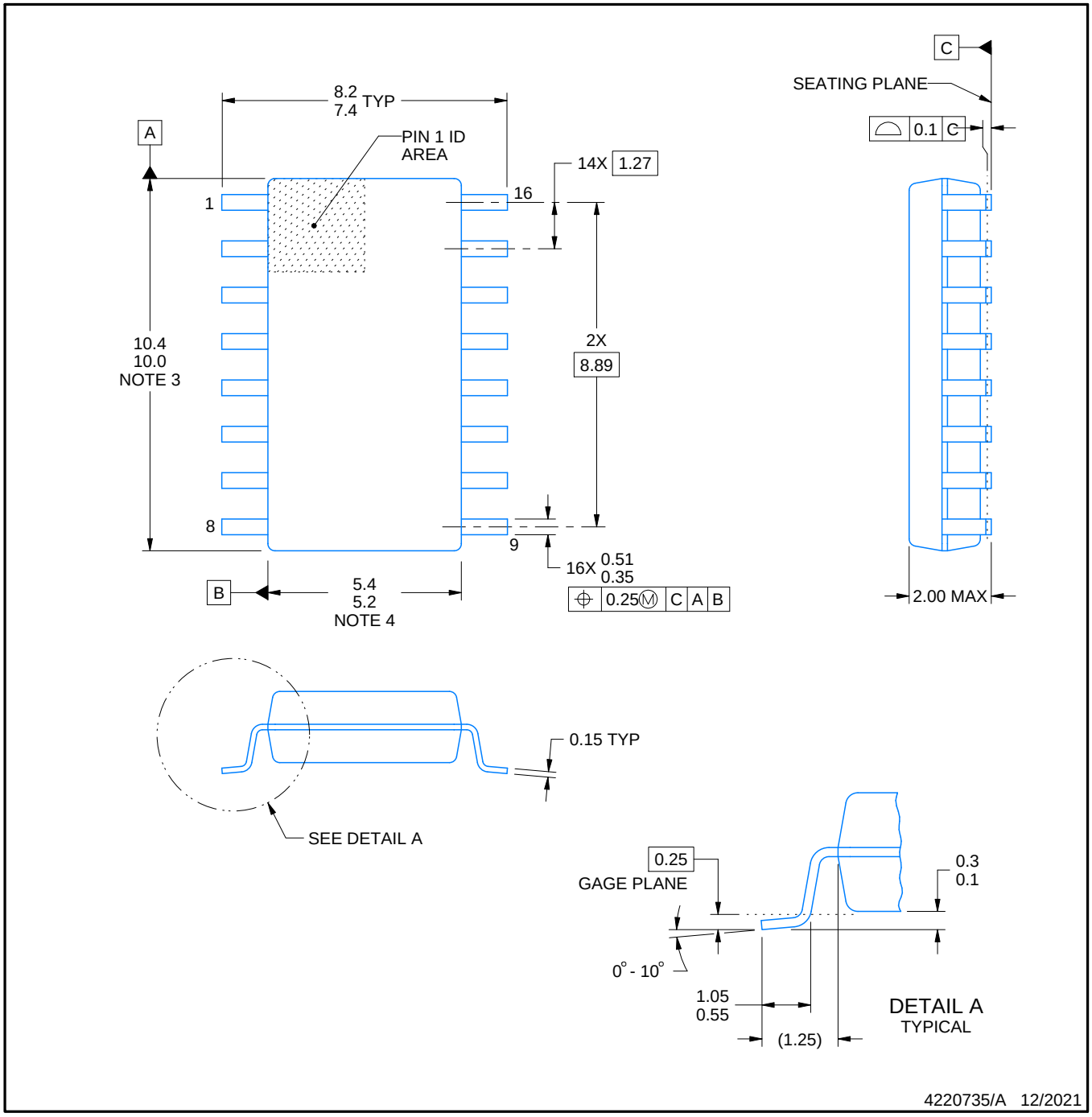


PACKAGE OUTLINE

NS0016A

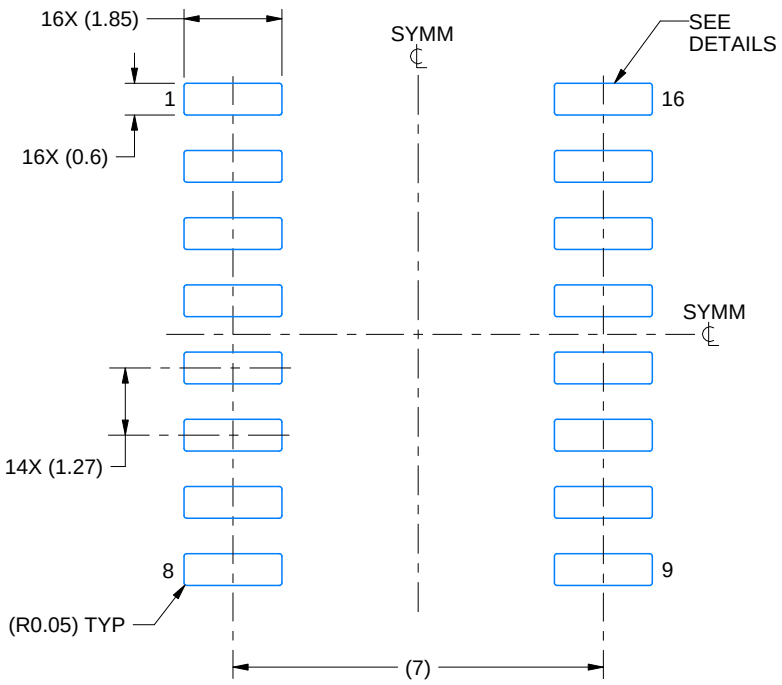
SOP - 2.00 mm max height

SOP

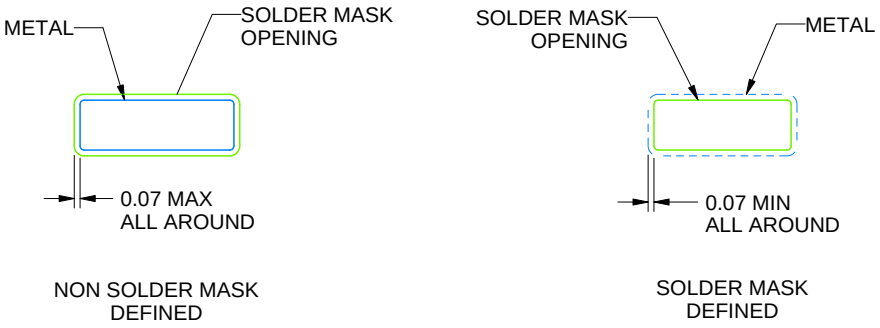


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

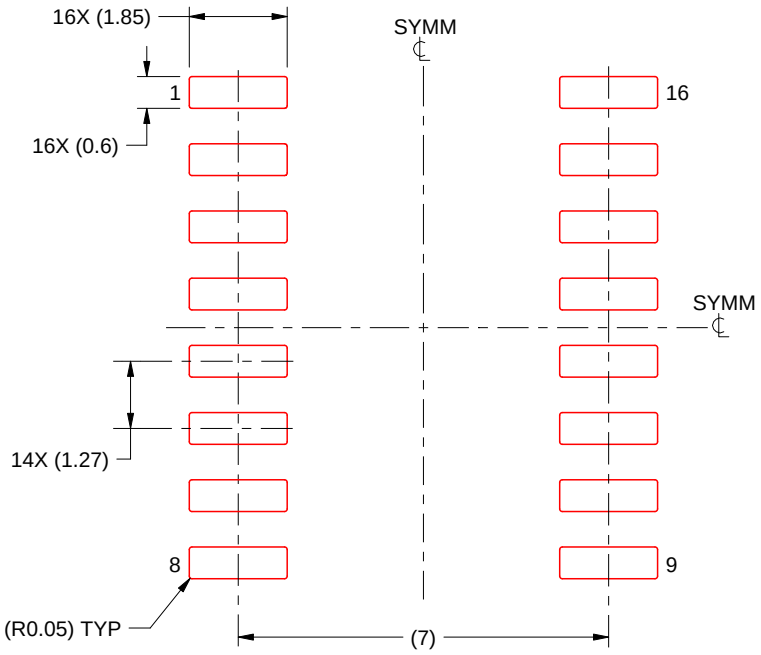
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265